

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yuji NAKAMURA	03/10/2009
RECEIVING PARTY DATA	
Name:	YAMAICHI ELECTRONICS CO., LTD.
Street Address:	28-7, Nakamagome 3-chome, Ohta-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	143-8515
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12446432
CORRESPONDENCE DATA	
Fax Number:	(202)408-4400
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202-408-4000
Email:	shaunette.mccoy@finnegan.com
Correspondent Name:	FINNEGAN, HENDERSON, FARABOW, GARRETT &
Address Line 1:	901 NEW YORK AVENUE, NW
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20001-4413
ATTORNEY DOCKET NUMBER:	04208.0281-00000
NAME OF SUBMITTER:	Shaunette E. McCoy
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PATENT
REEL: 022569 FRAME: 0069

Attorney Docket No.:

SOLE INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS, I, the below named inventor, (hereinafter referred to as Assignor), have made an invention entitled:

**CONTACT WITH SOLDER AND METHOD FOR MANUFACTURING THE
CONTACT**

for which I executed an application for United States Letters Patent concurrently herewith or on _____ or filed an application for United States Letters Patent on _____ (Serial No. _____); and

WHEREAS, Yamaichi Electronics Co., Ltd. , a corporation of Japan , whose post office address is 28-7, Nakamagome 3-chome, Ohta-ku, Tokyo 143-8515, Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application,

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I, as assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I HEREBY authorize and request the attorneys I have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____ filed _____) the filing date and application number of said application when known.

Attorney Docket No.:

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Assignor

Inventor: Yuji NAKAMURA

Residence: Tokyo, Japan

Citizenship: Japan

Signature: Yuji Nakamura

Date: March 10, 2009